

Amendments to the Claims:

The following listing of claims will replace all prior versions, and listings, of claims in the application:

- 1-15. (Canceled)
16. (Currently Amended) Microcomponent comprising a hermetically-sealed microcavity, delineated by a cover in which at least one hole is formed, and, on the cover, a sealing layer hermetically sealing the microcavity, the microcomponent comprising, under the sealing layer, a plug covering the hole and a part of the cover over the periphery of the hole, the sealing layer and the plug being formed by distinct materials, wherein the plug is made of ~~a material that is able to undergo creep deformation~~ polymer or of phosphosilicate glass.
17. (Canceled)
18. (Currently Amended) Microcomponent according to ~~claim 17~~ claim 16, wherein the ~~polymerized material~~ polymer is selected from photoresists and polyimide.
- 19-20. (Canceled)
21. (Previously Presented) Microcomponent according to claim 16, wherein the dimension of the hole is smaller than 5 micrometers.
22. (Previously Presented) Microcomponent according to claim 16, wherein the hole is arranged on the highest part of the microcavity.
23. (Previously Presented) Microcomponent according to claim 16, comprising a plurality of holes.
24. (Previously Presented) Microcomponent according to claim 16, wherein the thickness of the plug is comprised between 2 and 6 micrometers.
25. (Previously Presented) Microcomponent according to claim 16, wherein the plug comprises sloping sides.

26. (Previously Presented) Microcomponent according to claim 16, wherein the plug is non-hermetical.

27. (Previously Presented) Microcomponent according to claim 16, wherein the material of the sealing layer is selected from silicon dioxide, silicon nitride and metals.

28. (Previously Presented) Method for production of a hermetically-sealed microcavity of a microcomponent according to claim 16, successively comprising

- deposition of a sacrificial layer on a substrate,
 - deposition of a first layer forming the cover, on the substrate and sacrificial layer,
 - etching, in the cover, of at least one hole opening out onto the sacrificial layer,
 - removal of the sacrificial layer, via the hole, so as to create the microcavity,
 - deposition of the sealing layer, so as to seal the microcavity hermetically,
- method comprising deposition of the plug covering the hole and a part of the cover over the periphery of the hole, after the sacrificial layer has been removed and before the sealing layer is deposited.

29. (Currently Amended) ~~Method according to claim 28,~~ A Method for production of a hermetically-sealed microcavity of a microcomponent, successively comprising:

- deposition of a sacrificial layer on a substrate;
- deposition of a first layer forming the cover, on the substrate and sacrificial layer;
- etching, in the cover, of at least one hole opening out onto the sacrificial layer;
- removal of the sacrificial layer, via the hole, so as to create the microcavity;

- deposition of the sealing layer, so as to seal the microcavity hermetically;
the method comprising deposition of a plug covering the hole and a part of the
cover over the periphery of the hole, after the sacrificial layer has been removed and before
the sealing layer is deposited;

wherein, the plug is made of phosphosilicate glass, and the plug is obtained by
a method selected from solgel methods and cathode sputtering.

30. (Previously Presented) Method according to claim 28, wherein the plug is made of a porous material.

31. (Currently Amended) ~~Method according to claim 30,~~ A Method for
production of a hermetically-sealed microcavity of a microcomponent, successively
comprising:

- deposition of a sacrificial layer on a substrate;

- deposition of a first layer forming the cover, on the substrate and sacrificial
layer;

- etching, in the cover, of at least one hole opening out onto the sacrificial
layer;

- removal of the sacrificial layer, via the hole, so as to create the microcavity;

- deposition of the sealing layer, so as to seal the microcavity hermetically;

the method comprising deposition of a plug covering the hole and a part of the
cover over the periphery of the hole, after the sacrificial layer has been removed and before
the sealing layer is deposited;

wherein the plug is made of a porous material; and

wherein, the porous material is a photoresist, and the method comprises a high
temperature annealing step.

32. (Previously Presented) Method according to claim 30, wherein the method comprises a pumping step of the gas contained in the microcavity, through the porous material, before the sealing layer is deposited.

33. (New) Microcomponent according to claim 16, wherein the microcavity encloses a electromechanical microsystem.